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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. Of: MATSUDA

Serial No. 09/222,524

Filed: December 28, 1998

For: SEMICONDUCTOR DEVICE

Group: 2811

Examiner: NITIN PAREKH

DOCKET: NEC N8039 CON

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TECHNOLOGY CENTER 8800

The Assistant Commissioner of Patents & Trademarks  
Washington, D.C. 20231

Dear Sir:

AMENDMENT F

This Amendment is being filed in response to the Official Action mailed  
December 13, 2002. Please amend the Application as follows:

IN THE CLAIMS:

Please amend independent claims 21-23, 27-29, 33-35 and 39-41 to read as follows:

- f1  
Sub  
G1
21. (Thrice Amended) A semiconductor device comprising:
- a wiring substrate having a predetermined pattern of wiring formed on one surface;
  - a semiconductor chip disposed on the other surface of said wiring substrate and having at least one chip electrode set comprising at least two chip electrodes in a common wiring layer of said semiconductor chip, wherein said chip electrodes are arranged from an edge of said semiconductor chip toward its inner side;
  - said wiring substrate having a number of through-holes;

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